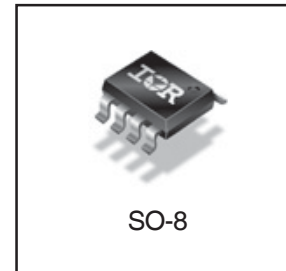
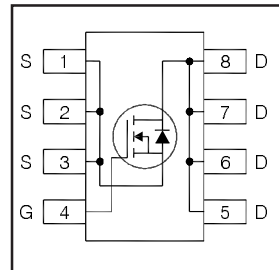


# IRF6201PbF

HEXFET® Power MOSFET

|                                                             |             |           |
|-------------------------------------------------------------|-------------|-----------|
| <b>V<sub>DS</sub></b>                                       | <b>20</b>   | <b>V</b>  |
| <b>R<sub>DS(on)</sub> max</b><br>(@ V <sub>GS</sub> = 4.5V) | <b>2.45</b> | <b>mΩ</b> |
| <b>R<sub>DS(on)</sub> max</b><br>(@ V <sub>GS</sub> = 2.5V) | <b>2.75</b> | <b>mΩ</b> |
| <b>Q<sub>g</sub> (typical)</b>                              | <b>130</b>  | <b>nC</b> |
| <b>I<sub>D</sub></b><br>(@ T <sub>A</sub> = 25°C)           | <b>27</b>   | <b>A</b>  |



## Applications

- OR-ing or hot-swap MOSFET
- Battery operated DC motor inverter MOSFET
- System/Load switch

## Features and Benefits

### Features

|                                                              |
|--------------------------------------------------------------|
| Low R <sub>DS(on)</sub> (≤ 2.45mΩ @ V <sub>gs</sub> = 4.5V)  |
| Industry-standard SO-8 package                               |
| RoHS compliant containing no lead, no bromide and no halogen |

results in  
⇒

### Benefits

|                            |
|----------------------------|
| Lower conduction losses    |
| Multi-vendor compatibility |
| Environmentally Friendly   |

| Orderable part number | Package Type | Standard Pack |          | Note |
|-----------------------|--------------|---------------|----------|------|
|                       |              | Form          | Quantity |      |
| IRF6201PbF            | SO8          | Tube/Bulk     | 95       |      |
| IRF6201TRPbF          | SO8          | Tape and Reel | 4000     |      |

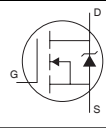
## Absolute Maximum Ratings

|                                        | Parameter                                           | Max.         | Units |
|----------------------------------------|-----------------------------------------------------|--------------|-------|
| V <sub>DS</sub>                        | Drain-to-Source Voltage                             | 20           | V     |
| V <sub>GS</sub>                        | Gate-to-Source Voltage                              | ±12          |       |
| I <sub>D</sub> @ T <sub>A</sub> = 25°C | Continuous Drain Current, V <sub>GS</sub> @ 4.5V    | 27           | A     |
| I <sub>D</sub> @ T <sub>A</sub> = 70°C | Continuous Drain Current, V <sub>GS</sub> @ 4.5V    | 22           |       |
| I <sub>DM</sub>                        | Pulsed Drain Current ①                              | 110          |       |
| P <sub>D</sub> @ T <sub>A</sub> = 25°C | Power Dissipation ③                                 | 2.5          | W     |
| P <sub>D</sub> @ T <sub>A</sub> = 70°C | Power Dissipation ③                                 | 1.6          |       |
|                                        | Linear Derating Factor                              | 0.02         | W/°C  |
| T <sub>J</sub><br>T <sub>STG</sub>     | Operating Junction and<br>Storage Temperature Range | -55 to + 150 | °C    |

## Static @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

|                              | Parameter                            | Min. | Typ. | Max. | Units                | Conditions                                                 |
|------------------------------|--------------------------------------|------|------|------|----------------------|------------------------------------------------------------|
| $BV_{DSS}$                   | Drain-to-Source Breakdown Voltage    | 20   | —    | —    | V                    | $V_{GS} = 0V$ , $I_D = 250\mu A$                           |
| $\Delta BV_{DSS}/\Delta T_J$ | Breakdown Voltage Temp. Coefficient  | —    | 4.6  | —    | mV/ $^\circ\text{C}$ | Reference to $25^\circ\text{C}$ , $I_D = 1\text{mA}$       |
| $R_{DS(on)}$                 | Static Drain-to-Source On-Resistance | —    | 1.90 | 2.45 | m $\Omega$           | $V_{GS} = 4.5V$ , $I_D = 27A$ ②                            |
|                              |                                      | —    | 2.10 | 2.75 |                      | $V_{GS} = 2.5V$ , $I_D = 22A$ ②                            |
| $V_{GS(th)}$                 | Gate Threshold Voltage               | 0.5  | —    | 1.1  | V                    | $V_{DS} = V_{GS}$ , $I_D = 100\mu A$                       |
| $I_{DSS}$                    | Drain-to-Source Leakage Current      | —    | —    | 1.0  | $\mu A$              | $V_{DS} = 16V$ , $V_{GS} = 0V$                             |
|                              |                                      | —    | —    | 150  |                      | $V_{DS} = 16V$ , $V_{GS} = 0V$ , $T_J = 125^\circ\text{C}$ |
| $I_{GSS}$                    | Gate-to-Source Forward Leakage       | —    | —    | 100  | nA                   | $V_{GS} = 12V$                                             |
|                              | Gate-to-Source Reverse Leakage       | —    | —    | -100 |                      | $V_{GS} = -12V$                                            |
| $Q_g$                        | Total Gate Charge                    | —    | 130  | 195  | nC                   | $V_{GS} = 4.5V$                                            |
| $Q_{gs}$                     | Gate-to-Source Charge                | —    | 16   | —    |                      | $V_{DS} = 10V$                                             |
| $Q_{gd}$                     | Gate-to-Drain Charge                 | —    | 60   | —    |                      | $I_D = 22A$                                                |
| $t_{d(on)}$                  | Turn-On Delay Time                   | —    | 29   | —    | ns                   | $V_{DD} = 20V$ , $V_{GS} = 4.5V$                           |
| $t_r$                        | Rise Time                            | —    | 100  | —    |                      | $I_D = 1.0A$                                               |
| $t_{d(off)}$                 | Turn-Off Delay Time                  | —    | 320  | —    |                      | $R_G = 6.8\Omega$                                          |
| $t_f$                        | Fall Time                            | —    | 265  | —    |                      | See Figs. 10a & 10b                                        |
| $C_{iss}$                    | Input Capacitance                    | —    | 8555 | —    | pF                   | $V_{GS} = 0V$                                              |
| $C_{oss}$                    | Output Capacitance                   | —    | 1735 | —    |                      | $V_{DS} = 16V$                                             |
| $C_{rss}$                    | Reverse Transfer Capacitance         | —    | 1290 | —    |                      | $f = 1.0\text{MHz}$                                        |

## Diode Characteristics

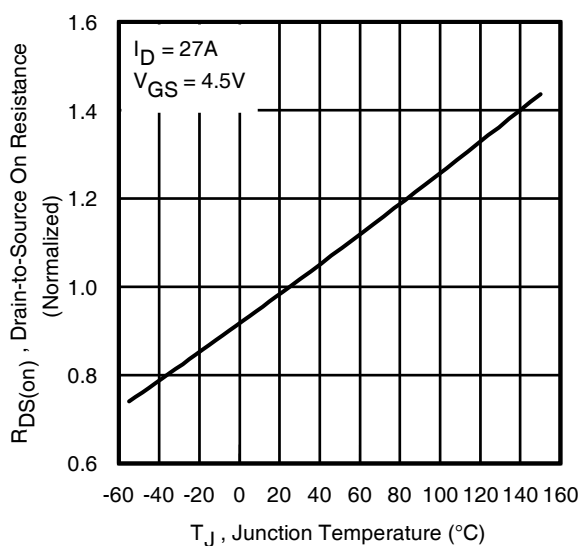
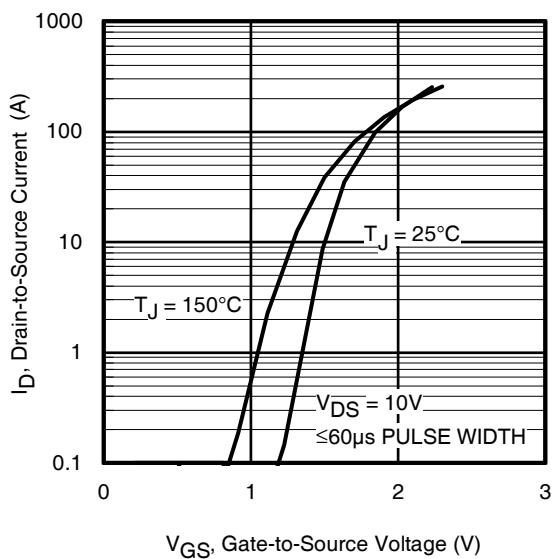
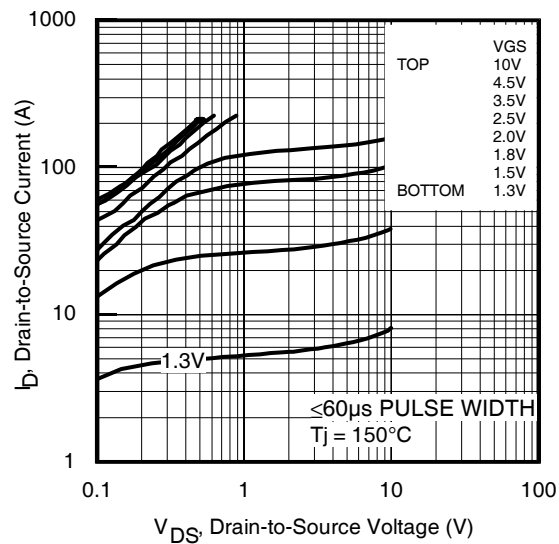
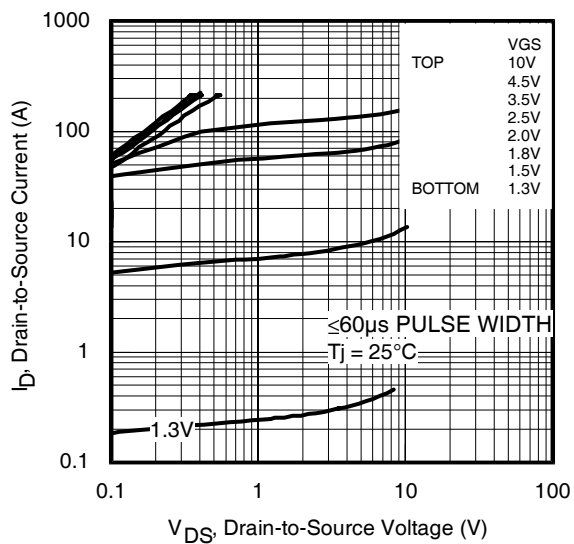
|          | Parameter                                 | Min. | Typ. | Max. | Units | Conditions                                                                                                                                           |
|----------|-------------------------------------------|------|------|------|-------|------------------------------------------------------------------------------------------------------------------------------------------------------|
| $I_S$    | Continuous Source Current<br>(Body Diode) | —    | —    | 2.5  | A     | MOSFET symbol showing the integral reverse p-n junction diode.  |
| $I_{SM}$ | Pulsed Source Current<br>(Body Diode) ①   | —    | —    | 110  |       |                                                                                                                                                      |
| $V_{SD}$ | Diode Forward Voltage                     | —    | —    | 1.2  | V     | $T_J = 25^\circ\text{C}$ , $I_S = 2.5A$ , $V_{GS} = 0V$ ②                                                                                            |
| $t_{rr}$ | Reverse Recovery Time                     | —    | 82   | 120  | ns    | $T_J = 25^\circ\text{C}$ , $I_F = 2.5A$ , $V_{DD} = 16V$                                                                                             |
| $Q_{rr}$ | Reverse Recovery Charge                   | —    | 180  | 270  | nC    | $di/dt = 100/\mu s$ ②                                                                                                                                |

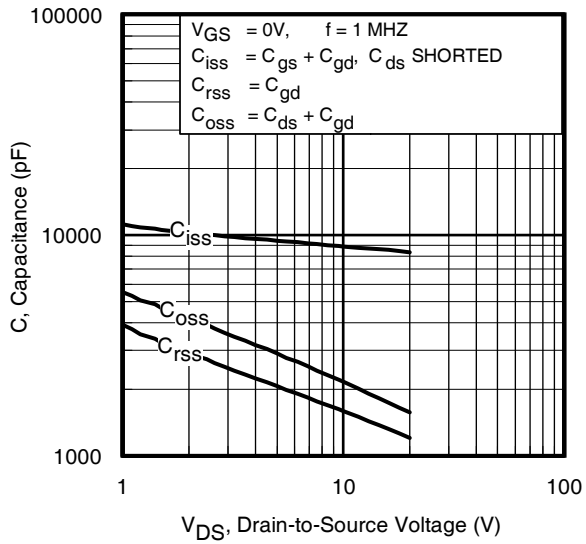
## Thermal Resistance

|                 | Parameter                | Typ. | Max. | Units              |
|-----------------|--------------------------|------|------|--------------------|
| $R_{\theta JL}$ | Junction-to-Drain Lead ④ | —    | 20   | $^\circ\text{C/W}$ |
| $R_{\theta JA}$ | Junction-to-Ambient ③    | —    | 50   |                    |

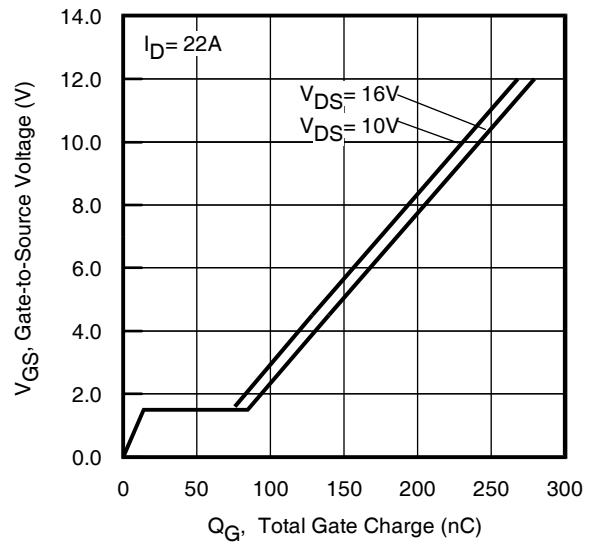
### Notes:

- ① Repetitive rating; pulse width limited by max. junction temperature.
- ② Pulse width  $\leq 400\mu s$ ; duty cycle  $\leq 2\%$ .
- ③ When mounted on 1 inch square copper board.
- ④  $R_\theta$  is measured at  $T_J$  approximately  $90^\circ\text{C}$ .

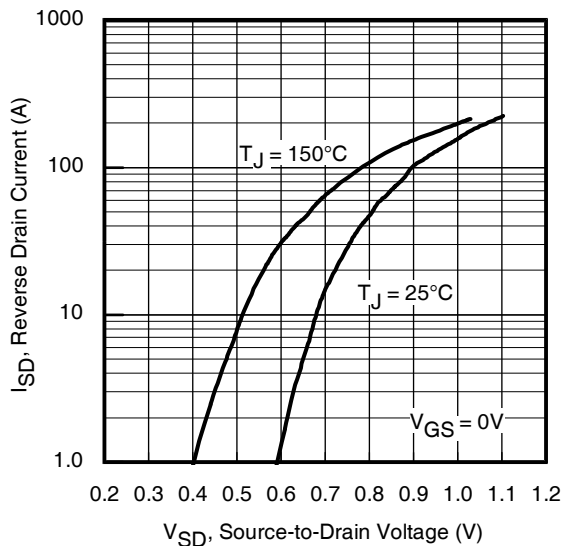




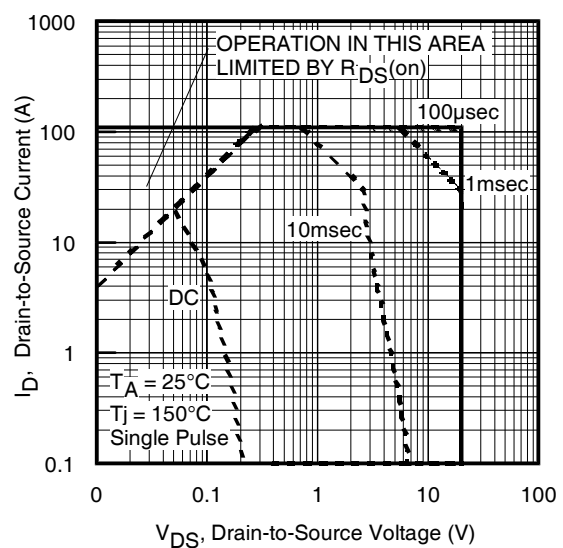
**Fig 5.** Typical Capacitance vs. Drain-to-Source Voltage



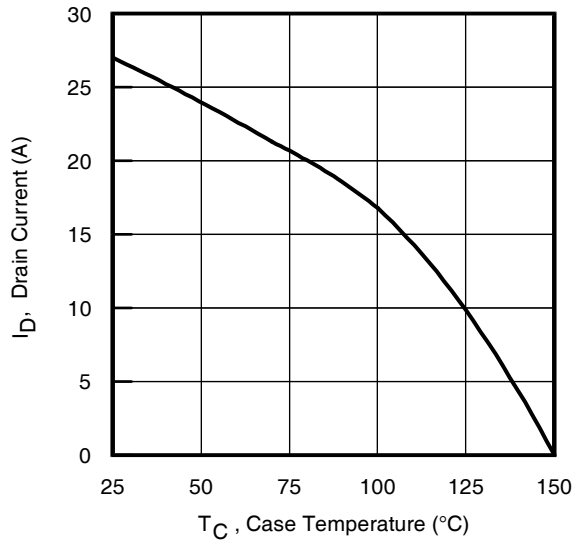
**Fig 6.** Typical Gate Charge vs. Gate-to-Source Voltage



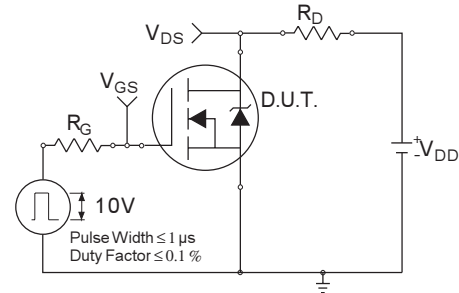
**Fig 7.** Typical Source-Drain Diode Forward Voltage



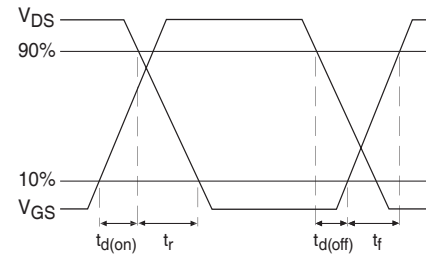
**Fig 8.** Maximum Safe Operating Area



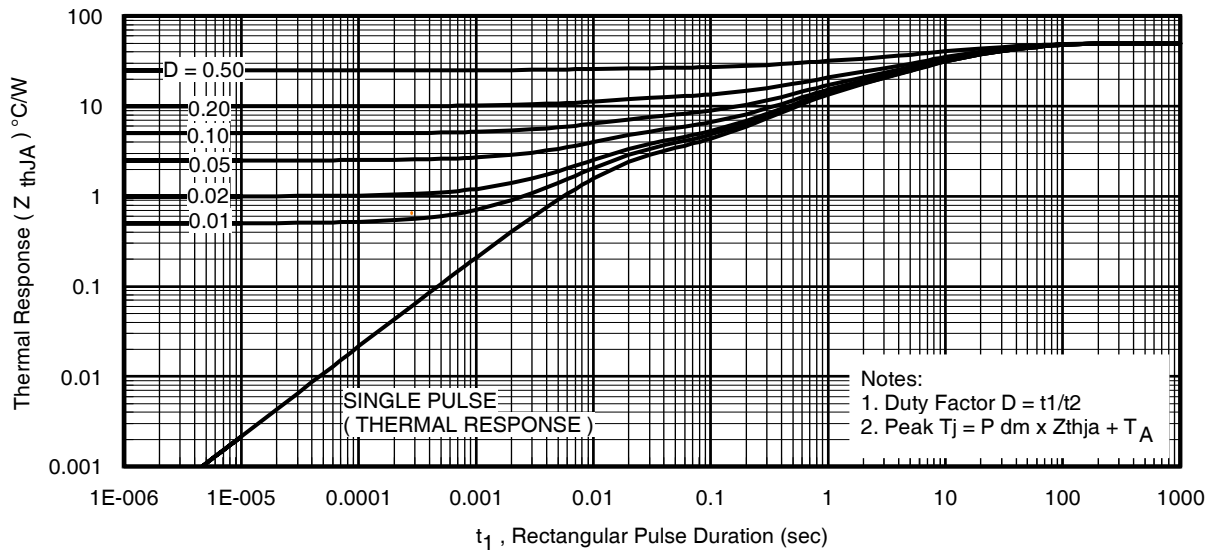
**Fig 9.** Maximum Drain Current vs. Case Temperature



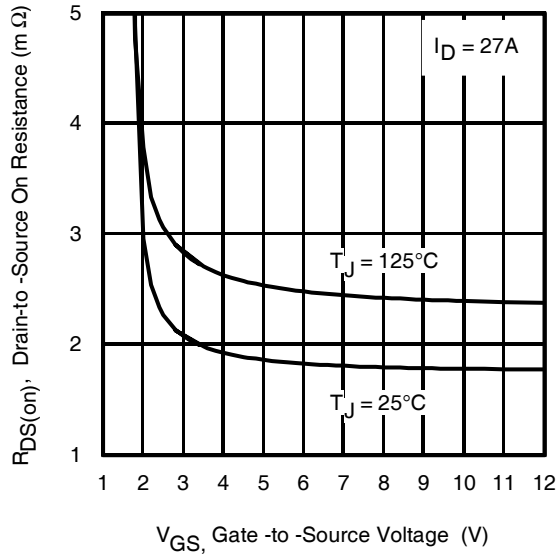
**Fig 10a.** Switching Time Test Circuit



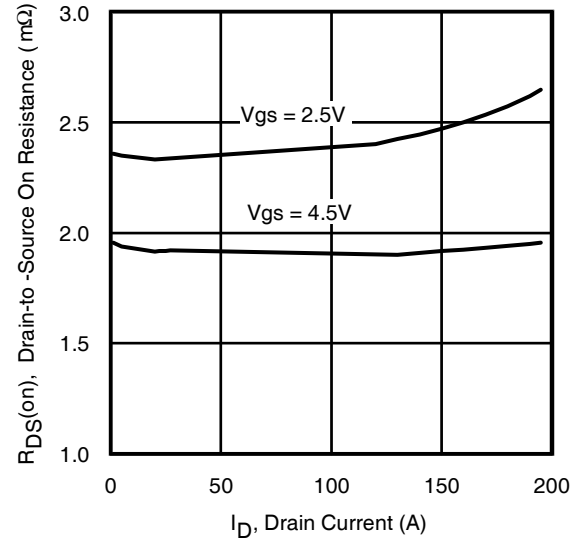
**Fig 10b.** Switching Time Waveforms



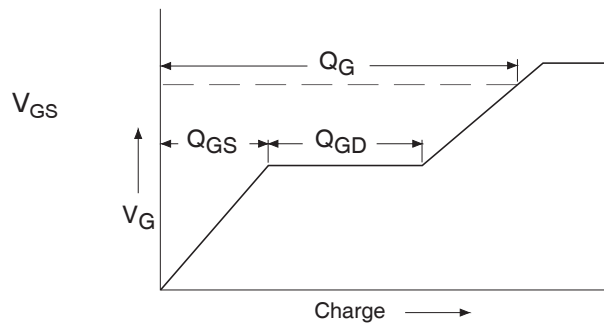
**Fig 11.** Typical Effective Transient Thermal Impedance, Junction-to-Ambient



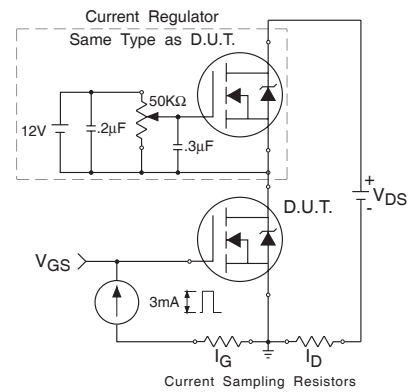
**Fig 12.** Typical On-Resistance vs. Gate Voltage



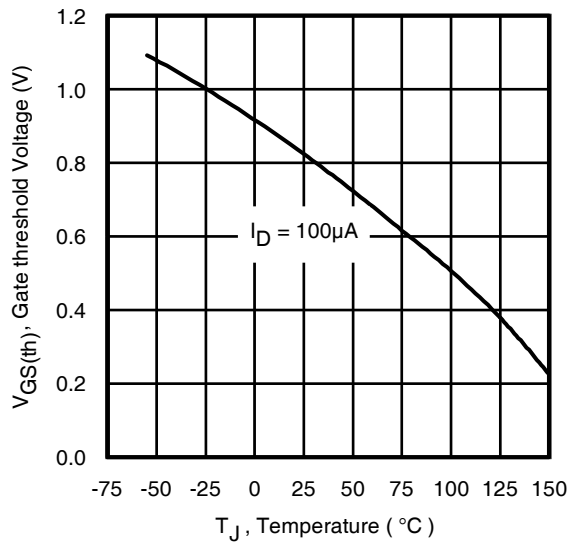
**Fig 13.** Typical On-Resistance vs. Drain Current



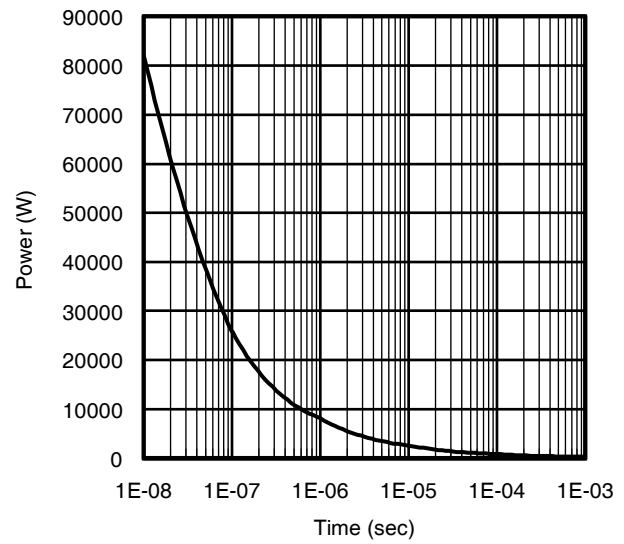
**Fig 14a.** Basic Gate Charge Waveform



**Fig 14b.** Gate Charge Test Circuit



**Fig 15.** Typical Threshold Voltage vs. Junction Temperature

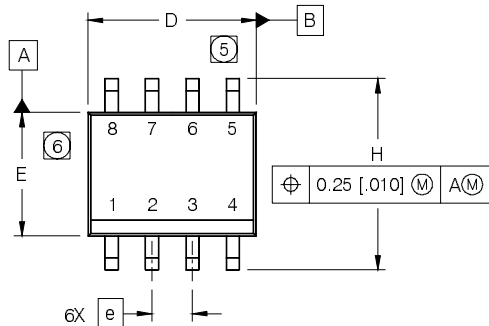


**Fig 16.** Typical Power vs. Time

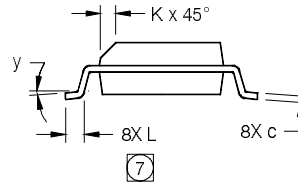
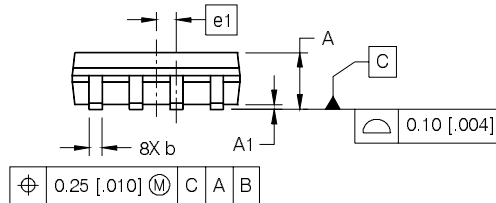
# IRF6201PbF

## SO-8 Package Outline (Mosfet & Fetky)

Dimensions are shown in millimeters (inches)



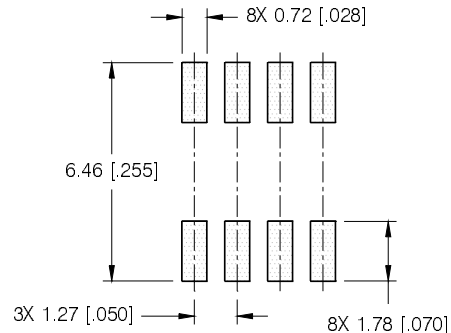
| DIM | INCHES     |       | MILLIMETERS |      |
|-----|------------|-------|-------------|------|
|     | MIN        | MAX   | MIN         | MAX  |
| A   | .0532      | .0688 | 1.35        | 1.75 |
| A1  | .0040      | .0098 | 0.10        | 0.25 |
| b   | .013       | .020  | 0.33        | 0.51 |
| c   | .0075      | .0098 | 0.19        | 0.25 |
| D   | .189       | .1968 | 4.80        | 5.00 |
| E   | .1497      | .1574 | 3.80        | 4.00 |
| e   | .050 BASIC |       | 1.27 BASIC  |      |
| e1  | .025 BASIC |       | 0.635 BASIC |      |
| H   | .2284      | .2440 | 5.80        | 6.20 |
| K   | .0099      | .0196 | 0.25        | 0.50 |
| L   | .016       | .050  | 0.40        | 1.27 |
| y   | 0°         | 8°    | 0°          | 8°   |



### NOTES:

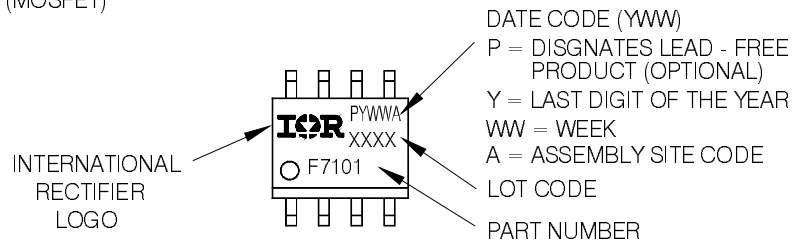
1. DIMENSIONING & TOLERANCING PER ASME Y14.5M-1994.
2. CONTROLLING DIMENSION: MILLIMETER
3. DIMENSIONS ARE SHOWN IN MILLIMETERS [INCHES].
4. OUTLINE CONFORMS TO JEDEC OUTLINE MS-012AA.
5. DIMENSION DOES NOT INCLUDE MOLD PROTRUSIONS. MOLD PROTRUSIONS NOT TO EXCEED 0.15 [0.006].
6. DIMENSION DOES NOT INCLUDE MOLD PROTRUSIONS. MOLD PROTRUSIONS NOT TO EXCEED 0.25 [0.010].
7. DIMENSION IS THE LENGTH OF LEAD FOR SOLDERING TO A SUBSTRATE.

### FOOTPRINT



## SO-8 Part Marking Information

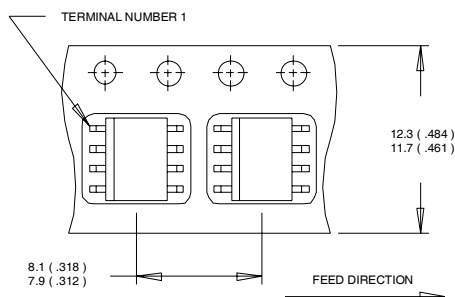
EXAMPLE: THIS IS AN IRF7101 (MOSFET)



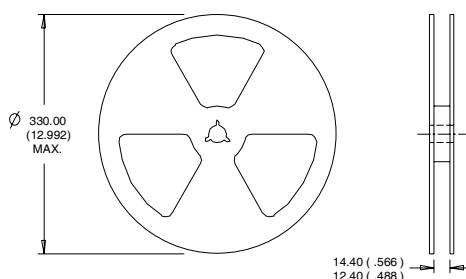
Note: For the most current drawing please refer to IR website at <http://www.irf.com/package/>



## SO-8 Tape and Reel



NOTES:  
1. CONTROLLING DIMENSION : MILLIMETER.  
2. ALL DIMENSIONS ARE SHOWN IN MILLIMETERS(INCHES).  
3. OUTLINE CONFORMS TO EIA-481 & EIA-541.



NOTES :  
1. CONTROLLING DIMENSION : MILLIMETER.  
2. OUTLINE CONFORMS TO EIA-481 & EIA-541.

### Qualification Information<sup>†</sup>

|                            |                                                                         |                                                |
|----------------------------|-------------------------------------------------------------------------|------------------------------------------------|
| Qualification level        | Consumer <sup>††</sup><br>(per JEDEC JESD47F <sup>†††</sup> guidelines) |                                                |
| Moisture Sensitivity Level | SO-8                                                                    | MSL1<br>(per JEDEC J-STD-020D <sup>†††</sup> ) |
| RoHS Compliant             | Yes                                                                     |                                                |

<sup>†</sup> Qualification standards can be found at International Rectifier's web site

<http://www.irf.com/product-info/reliability>

<sup>††</sup> Higher qualification ratings may be available should the user have such requirements.

Please contact your International Rectifier sales representative for further information:

<http://www.irf.com/whoto-call/salesrep/>

<sup>†††</sup> Applicable version of JEDEC standard at the time of product release.

Data and specifications subject to change without notice.

International  
**IR** Rectifier

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TAC Fax: (310) 252-7903

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